

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

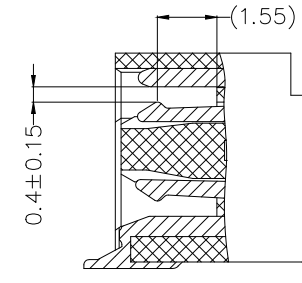
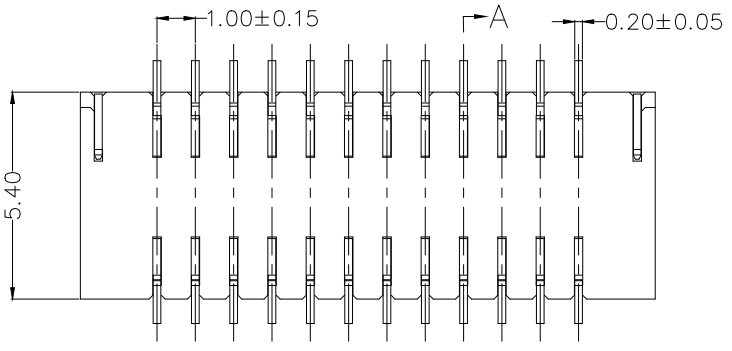
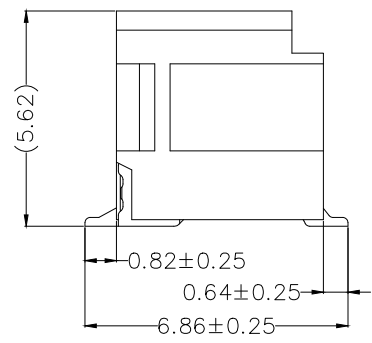
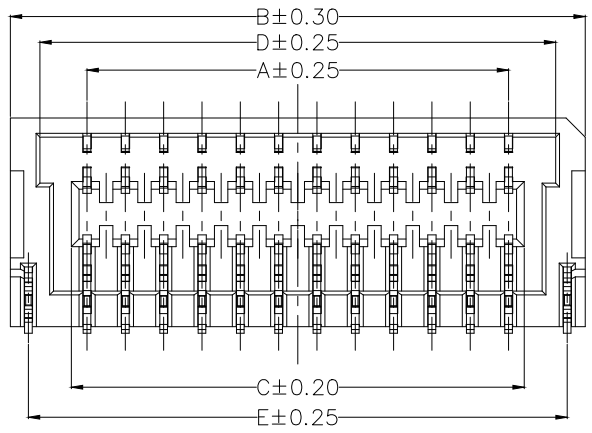
SPECIFICATIONS

Electrical

Current Rating: 1A AC/DC
Voltage Rating: 50V AC
Contact Resistance: $\leq 20\text{m}\Omega$ (Initial) per contact,
 $\leq 40\text{m}\Omega$ Change allowed.
Insulation Resistance: 100 M Ω MIN
Withstanding Voltage: 500V AC/MINUTE
Temperature Range-Operating: $-40^{\circ}\text{C} \sim +105^{\circ}\text{C}$

Material

Housing: LCP (UL94V-0), Natural
Terminal: Copper Alloy, Tin-Plated
Solder Tab: Copper Alloy, Tin-Plated
Mates With Housing: FHG10008 Series



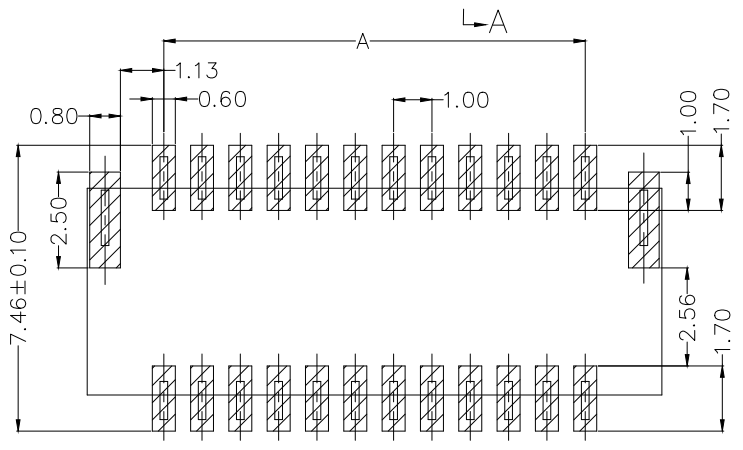
	0.10	Circuits 08~20
	0.12	Circuits 22~40

SEC: A-A

Ordering Information

FWF 100 13 - D XX B 8 3 NA M
1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 100-Pitch1.00mm	3 Distinction No. 13	4 Row Option D-Double row	5 Circuits XX
6 Entry Angle B-90° Angle	7 Plating 8-Bright tin Plated	8 Material-Resin 3-LCP	9 Color-Resin NA-Natural	10 Packaging M-Reel



Recommended P.C.Board Layout
Tolerance $\pm 0.05\text{mm}$

 THIRD ANGLE PROJECTION DESIGN UNITS mm SCALE 5:1 SIZE A4	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 03/NOV/21	PART NO. FWF10013-DXXB83NAM	ITEM NO. FWF10013	 Building Technology Cornerstone REV 0 SHEET NO. 1/3
	X. ± 0.30	X.* $\pm 5^{\circ}$	CHECKED BY GISELLE	DATE 03/NOV/21	TITLE Wire to Board Pitch 1.00mm (Wafer)		
	X.X ± 0.20	X.X* $\pm 2^{\circ}$	DRAWN BY PYD	DATE 03/NOV/21	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	X.XX ± 0.15	X.XX* $\pm 1^{\circ}$					

1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

B

C

D

E

F

A

B

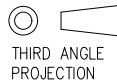

C

D

E

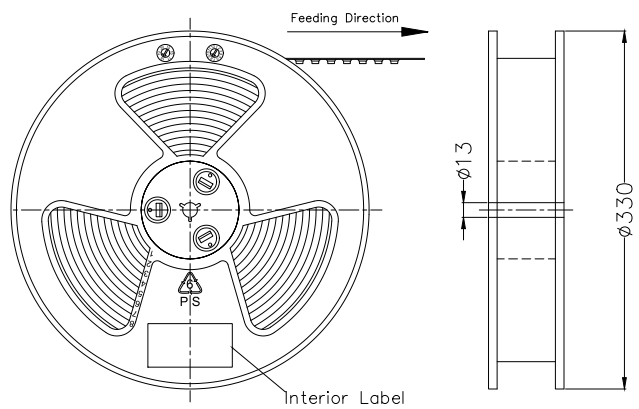
F

Circuits (n)	Part NO.	Dimensions				
		A	B	C	D	E
8	FWF10013-D08B83NAM	3.00	7.00	3.82	5.46	6.06
10	FWF10013-D10B83NAM	4.00	8.00	4.82	6.46	7.06
12	FWF10013-D12B83NAM	5.00	9.00	5.82	7.46	8.06
14	FWF10013-D14B83NAM	6.00	10.00	6.82	8.46	9.06
16	FWF10013-D16B83NAM	7.00	11.00	7.82	9.46	10.06
18	FWF10013-D18B83NAM	8.00	12.00	8.82	10.46	11.06
20	FWF10013-D20B83NAM	9.00	13.00	9.82	11.46	12.06
22	FWF10013-D22B83NAM	10.00	14.00	10.82	12.46	13.06
24	FWF10013-D24B83NAM	11.00	15.00	11.82	13.46	14.06
26	FWF10013-D26B83NAM	12.00	16.00	12.82	14.46	15.06
28	FWF10013-D28B83NAM	13.00	17.00	13.82	15.46	16.06
30	FWF10013-D30B83NAM	14.00	18.00	14.82	16.46	17.06
32	FWF10013-D32B83NAM	15.00	19.00	15.82	17.46	18.06
34	FWF10013-D34B83NAM	16.00	20.00	16.82	18.46	19.06
36	FWF10013-D36B83NAM	17.00	21.00	17.82	19.46	20.06
38	FWF10013-D38B83NAM	18.00	22.00	18.82	20.46	21.06
40	FWF10013-D40B83NAM	19.00	23.00	19.82	21.46	22.06

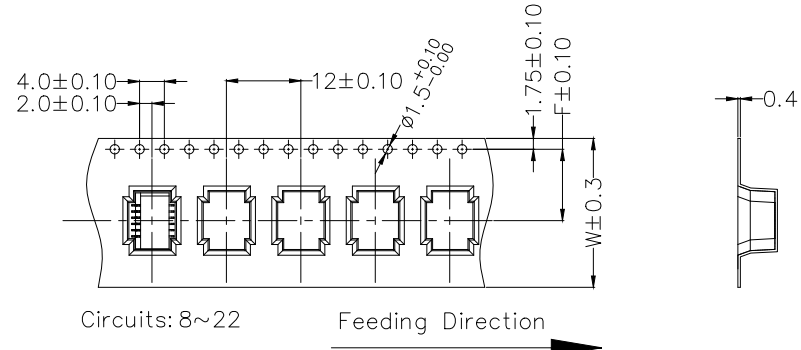
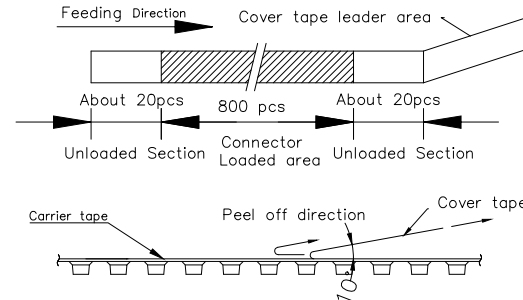
 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone	
	X. ±0.30	X.* ±5'	LEO	03/NOV/21	FWF10013-DXXB83NAM	FWF10013		
	DESIGN UNITS mm	X.X ±0.20	X.X' ±2'	CHECKED BY	DATE	TITLE		
	SCALE 5:1	X.XX ±0.15	X.XX' ±1'	GISELLE	03/NOV/21	Wire to Board Pitch 1.00mm (Wafer)		
SIZE A4	X.XXX ±0.10	X.XXX' ±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		REV 0	SHEET NO. 2/3
			PYD	03/NOV/21				

1 2 3 4 5 6 7 8

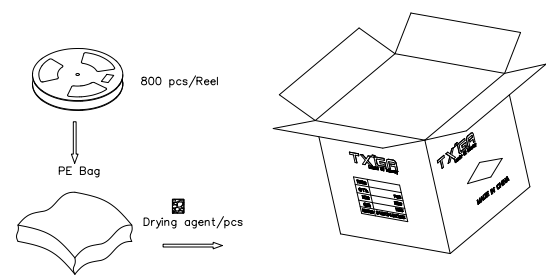
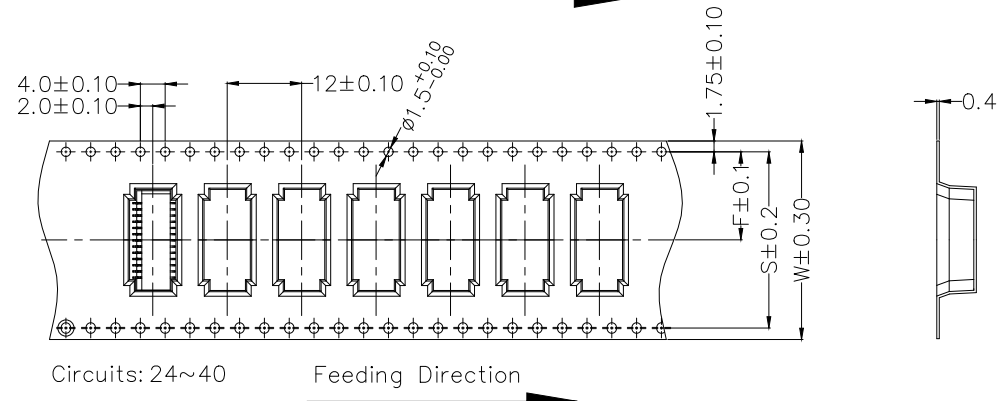
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- 10 sprocket hole cumulative tolerance ± 0.2
- Carrier camber is within 1.0mm in 250mm
- Material: Clear conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Peel off force of cover tape & carrier tape: 20g~130g (0.2N~1.3N)
- Component load per 13" reel: 800 pcs



Circuits (n)	Dimensions		
	W	S	F
8	16	—	7.5
10~22	24	—	11.5
24~36	32	28.4	14.2
38~40	44	40.4	20.2



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone	
	X. ±0.30	X.* ±5'	LEO	03/NOV/21	FWF10013-DXXB83NAM	FWF10013		
	DESIGN UNITS	X.X ±0.20	X.X' ±2'	CHECKED BY	DATE	TITLE		REV 0 SHEET NO. 3/3
	mm	X.XX ±0.15	X.XX' ±1'	GISELLE	03/NOV/21	Wire to Board Pitch 1.00mm (Wafer)		
SCALE	SIZE	X.XXX ±0.10	X.XXX' ±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4			PYD	03/NOV/21			